EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	0	("4862322"|"5074947"|"5214250"|"5267867"|"5290970"|"5367593"|"5382545"|"5579574"|"5627406"|"5700737"|"5841193"|"5918364"|"5972152"|"5998738"|"6103554"|"6138348"|"6141245"|"6174804"|"6246010"|"6246010"|"6372549"|"6372549"|"6515870"|"6515870"|"6528891"|"6528891"|"6664176"|"6846737"|"6846737").PN. and (circuit or device or semiconductor) and (substrate or wafer or base or carrier) and bump and (solder near9 well) and bond and (heat$4 or thermal$4) and (clean$4 or ash$4) and cool$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/19 13:06
L2	543	(circuit or device or semiconductor) and (substrate or wafer or base or carrier) and bump and (solder near9 well) and bond and (heat$4 or thermal$4) and (clean$4 or ash$4) and cool$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/19 13:08
L3	73	(circuit or device or semiconductor) and (substrate or wafer or base or carrier) and bump and (solder near9 well) and bond and (heat$4 or thermal$4) and (clean$4 or ash$4) and cool$4 and defect$4 and stud	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/19 13:08
L4	73	(circuit or device or semiconductor) and (substrate or wafer or base or carrier) and bump and (solder near9 well) and bond and (heat$4 or thermal$4) and (clean$4 or ash$4) and cool$4 and defect$4 and stud and bond	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/19 13:09
L5	8	(circuit or device or semiconductor) and (substrate or wafer or base or carrier) and bump and (solder near9 well) and bond and (heat$4 or thermal$4) and (clean$4 or ash$4) and cool$4 and defect$4 and stud and bond and (438/106.ccls.)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/19 13:10

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L6	8	(circuit or device or semiconductor) and (substrate or wafer or base or carrier) and bump and (solder near9 well) and bond and (heat$4 or thermal$4) and (clean$4 or ash$4 or wash$4) and cool$4 and defect$4 and stud and bond and (438/106. ccls.)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/19 13:11
S1	346	(substrate or semiconductor or wafer or carrier) near8 (dielectric or insulat$4 or oxide) and (interconnect$4 near4 circuit) and (I/O near4 pad) and wells and solder	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/19 13:04
S2	24	(substrate or semiconductor or wafer or carrier) near8 (dielectric or insulat$4 or oxide) and (interconnect$4 near4 circuit) and ((I/O near4 pad) near8 wells) and solder	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/25 11:09
S3	0	(substrate or semiconductor or wafer or carrier) near8 (dielectric or insulat$4 or oxide) and (interconnect$4 near4 circuit) and ((I/O near4 pad) near8 wells) and solder and squegee	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/25 10:49
S4	8	(substrate or semiconductor or wafer or carrier) near8 (dielectric or insulat$4 or oxide) and (interconnect$4 near4 circuit) and ((I/O near4 pad) near8 wells) and solder and squeegee	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/25 10:49
S5	1	(glass near4 (substrate or semiconductor or wafer or carrier)) near8 (dielectric or insulat$4 or oxide) and (interconnect$4 near4 circuit) and ((I/O near4 pad) near8 wells) and solder	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/25 10:56
S6	7	(substrate or semiconductor or wafer or carrier) near8 (dielectric or insulat$4 or oxide) and (interconnect$4 near4 circuit) and ((I/O near4 pad) near8 wells) and ((conductive or metal or solder) near4 bond)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/25 12:33

S7	17	"6141245"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/25 12:37
S8	5719	trace near4 rout$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/25 12:37
S9	1357	(trace near4 rout$4) and (interconnect$4 near4 circuit)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/25 12:38
S10	55	(trace near4 rout$4) and (multiple near4 (interconnect$4 near4 circuit))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/25 12:39
S11	5	(trace near4 rout$4) and (multiple near4 (interconnect$4 near4 circuit)) and level near4 contact	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/25 12:49
S12	0	("5214250"|"5267867"|"5290970"|"5579574"|"5627406"|"5972152"|"5998738"|"6103554"|"6141245"|"6246010"|"6372549"|"6515870"|"6528891"|"6664176"|"6846737").PN. and S11	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/25 12:51
S13	2	("5214250"|"5267867"|"5290970"|"5579574"|"5627406"|"5972152"|"5998738"|"6103554"|"6141245"|"6246010"|"6372549"|"6515870"|"6528891"|"6664176"|"6846737").PN. and S7	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/25 12:51